

**Amendments to the Claims:**

The following Listing of Claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims**

1. (Currently Amended) A multi-layer double-sided wiring board comprising:  
an insulating layer having an opening formed therein;  
a first conductive layer formed on an upper surface of the insulating layer;  
a second conductive layer formed on a lower surface of the insulating layer and covering an inside wall of the opening and a portion of the first conductive layer which is exposed in the opening; and

an interface layer interposed between the insulating layer and at least a portion of one or both of the first and second conductive layers including the portion of the second conductive layer covering an inside wall of the opening, and wherein

the first and second conductive layers are materials having the same conductivity,  
the interface layer contains a material different from the materials of the first and second conductive layers, and

the second conductive layer directly contacts the first conductive layer in the portion of the opening adjacent the upper surface of the insulating layer without the interface layer being interposed therebetween.

2. (Canceled)

3. (Previously Presented) A multi-layer double-sided wiring board according to claim 1, wherein the interface layer contains at least one metallic element selected from the group consisting of nickel, cobalt, zinc, and chromium.

4. (Original) A method of fabricating a multi-layer double-sided wiring board, comprising the steps of:

selectively removing a portion of an insulating layer on an upper surface of which is formed a conductive layer, and thereby forming in the insulating layer an opening whose upper end is closed with the conductive layer;

forming an interface layer over an entire lower surface;

selectively removing at least a portion of the interface layer which contacts the first conductive layer; and

forming a conductive layer over the entire lower surface.

5. (Canceled)

6. (Previously presented) A multi-layer double-sided wiring board according to claim 1, wherein the first and second conductive layers are made of the same material.

7. (Previously presented) A multi-layer double-sided wiring board according to claim 1, wherein the first and second conductive layers are made of copper.